

	Type	L #	Hits	Search Text	DBs	Time Stamp	C o m m e n t s	E r r o r s	E r r o r s
1	BRS	L8	569	((abrasi\$2 adj2 free) or (slurry near3 (free or without or "none" or "no"))) same (polish\$3 or planariz\$5)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/25 11:11			0
2	BRS	L15	210	8 and 438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/25 13:18			0
3	BRS	L22	210	15 and Pd<=19980831	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/25 11:14			0
4	BRS	L29	26	15 and @Pd<=19980831	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/25 12:00			0
5	BRS	L36	0	"A New Abrasive-Free, Chemical-Mechanical-Polishing Technique for Aluminum Metallization of ULSI Devices"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/25 12:04			0
6	BRS	L43	84	(AF or AFP) same (cmp or polish\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/25 12:05			0
7	BRS	L50	184	15 not 29	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/25 12:52			0
8	BRS	L57	49	8 and 252/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/25 13:18			0

	Type	L #	Hits	Search Text	DBs	Time Stamp	C o m m e n t s	E r r o r s
9	BRS	L64	2217	57 mot 50	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/25 13:21		0
10	BRS	L71	24	57 not 50	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/25 13:18		0